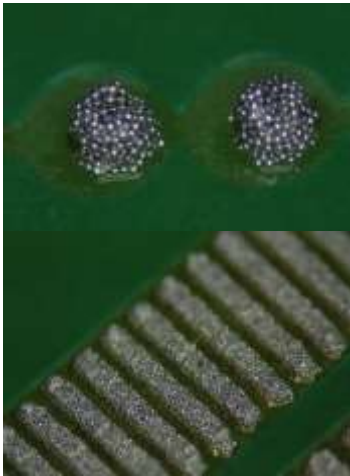
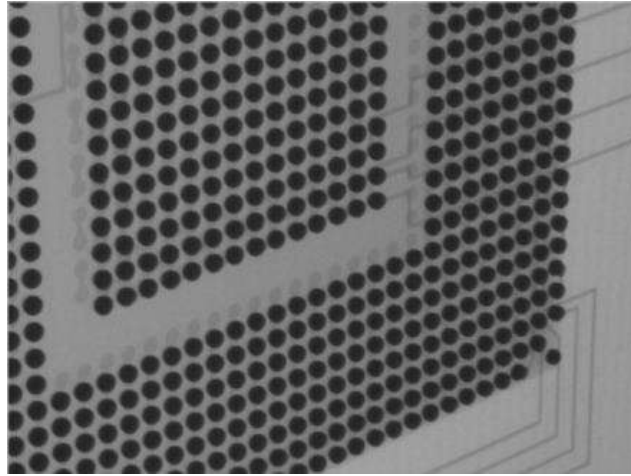


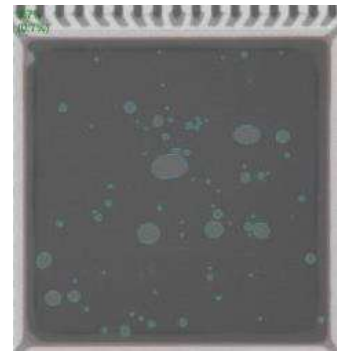
SHENMAO Introduces New Generation Lead-Free Solder Paste PF606-P140 to solve HoP issues and improve ICT Testability at SMTAI Exhibition: September 19-20, 2017 booth # 534 Donald Stephens Convention Center, Rosemont, IL



Superior Print Quality



Prevents Head in Pillow Issue



**3.7 %
Industry
Lowest Void
Performance**

SHENMAO Technology, Inc. introduces New Generation Lead-free Solder Paste **PF606-P140**. With superior continuous high-speed printability producing great Solder Paste Print Quality and a wide reflow process window for excellent solderability, it prevents Head on Pillow issues and can easily fit into highly complicated PCB designs through excellent convergence performance.

SHENMAO PF606-P140 improves ICT testability with flux completely removed from top of solder to prevent contamination of Test Pins during Test operation. Minimal Flux Residue gathers near outside of Solder Joint on the PCB Substrate, a substantial improvement over legacy solder Paste.

For more than 44 years, **SHENMAO** has been dedicated to produce Solder Products including Water Soluble and No-clean Solder Paste, Laser Solder Paste, Solder Preforms, Cored Solder Wire, Wave Solder Bar Alloys, Wave Soldering Fluxes, Extremely Pure Solder Powder up to Type 8, BGA and Micro BGA Solder Sphere, Wafer Level Packaging Solder Paste and Fluxes, LED Die Attach Paste, High Performance Liquid Fluxes, Solder Preform, Solar Ribbon, Plating Anode used in PCB Fabrication, Assembly and Semiconductor Packaging Processes.

SHENMAO Solder Materials are available at affordable cost from 10 worldwide locations.

For more information, please contact: